

**AMENDMENTS TO THE SPECIFICATION:****Title:**

Please amend the title as follows:

SEMICONDUCTOR PACKAGING DEVICE ~~AND MANUFACTURE THEREOF~~

*On page 1 before BACKGROUND OF THE INVENTION, please insert the following paragraph:*

This application is a continuation application of U.S. Application No. 10/074,052.

*Please amend the paragraph beginning on page 1, at line 9 as follows:*

The invention relates to a stacking semiconductor packaging device and manufacture thereof, and more particularly relates to a ~~structure of flip-chip ball-grid array (FCBGA) and manufacture thereof~~ semiconductor packing device with a carrier for chip.

*Please amend the paragraph beginning on page 2, at line 15 as follows:*

It is another object of the present invention to provide improved structure of FCBGA and manufacture thereof. The redistribution and solder-bump process for a conventional structure of FCBGA are simplified and integrated into the fan-out process of build-up substrate.

*Please delete the paragraph on page 2, beginning at line 26 in its entirety and replace it with the following new paragraph:*

A semiconductor packaging device provides a carrier having at least a portion configured for containing a chip. The chip, affixing to the portion with sidewall, has a back surface an active surface, which multitudes of bonding pads are on the active surface. One insulating layer on the active surface and carrier has multitudes of conductive holes corresponding to the first bonding pads. A multi-layer structure on the insulating layer is configured for providing electrical connection to the conductive holes. Another insulating layer, affixed on one of the carrier and the multi-layer structure, has another conductive holes electrically connected to the

*[Handwritten signatures and date]*  
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